ABSTRACT

SYSTEM AND METHOD FOR FLUXLESS THERMOCOMPRESSION BONDING

A bonding system for bonding an electronic component to a base member includes a first container for forming a first inert environment where the base member is locatable during bonding of the electronic component. A first plasma cleaning device is located in the first container to clean the electronic component and/or the base member by removing metal oxides therefrom. A second plasma cleaning device is also provided to clean the electronic component by removing organic contaminants therefrom before the electronic component is conveyed into the first container. A bond head is movably installed in the first container to bond the electronic component to the base member after the electronic component and/or the base member have been cleaned by the first plasma cleaning device.

[FIG. 1A]